

银粉 Superfine silver powders

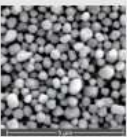
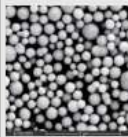
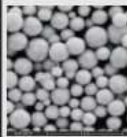
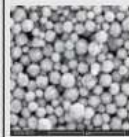
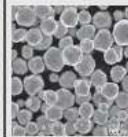
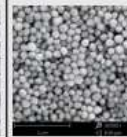
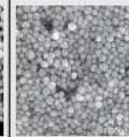
适用范围 Application

- 烧结型银浆，如TOPCon/PERC/xBC主栅、细栅浆料，厚膜电子浆料等
Sintered silver paste, both bus-bar and finger silver pastes for TOPCon/PERC/xBC cells, and thick film paste, etc.
- 低温固化浆料，如HJT、TP银浆等
Polymer silver paste, including HJT cell, TP silver paste.

亮点 Highlights

- 高低结晶度可调制，高烧结活性，导电性好
With controllable crystallinity and sintering activity, ensuring good conductivity.
- 粒径分布窄，适合细线印刷要求；尤其满足10微米以下线宽印刷
The narrow particle size distribution enables excellent fine-line printability, specifically satisfying the requirements for printing line widths below 10 μm .
- 表面性质可定制，以适配浆料流变需求、高速印刷需求
Surface-modified product can be customized to meet the rheological needs for high-speed printing.
- 兼容TOPCon、PERC、xBC电池主栅、细栅银浆
Superior printing performance that simultaneously ensures an excellent aspect ratio with clean, Compatible with both bus-bar and finger silver pastes for TOPCon/PERC/xBC cells.

典型产品（物性可定制） Typical products (Customized products can be developed)

	GS721	GS724	GS7406	GS7408	GS7510	GS7514	GS922	GS925
振实密度 Tap density (g/cm ³)	≥5.0	≥5.8	≥5.0	≥6.0	≥5.5	≥5.5	≥5.0	≥3.0
比表面积 Specific surface area (m ² /g)	0.60-0.80	0.35-0.50	0.45-0.70	0.30-0.45	0.45-0.65	0.30-0.50	1.0-2.0	4.0-7.0
粒度分布 PSD	D10, μm	< 0.8	< 1.0	< 0.8	< 1.0	< 0.8	< 1.0	< 0.3
	D50, μm	< 1.0	< 1.5	< 1.4	< 1.7	< 1.2	< 1.5	< 0.6
	D90, μm	< 2.0	< 3.0	< 3.5	< 4.0	< 2.2	< 3.5	< 1.0
	D100, μm	< 3.0	< 4.0	< 5.0	< 6.5	< 4.0	< 4.5	< 2.0
烧损 L.O.A (%)	≤0.40	≤0.40	0.40-0.70	0.40-0.70	0.40-1.00	0.40-1.00	≤0.60	≤1.80
SEM								
特点 Features	单晶、粒径均匀 Single-crystal structure with uniform particle size		多晶球形、粒径分布较宽 Polycrystalline spherical morphology with broad particle size distribution		结晶度、粒径均匀度可定制 Controllable crystallinity and particle size uniformity		纳米，高活性 Nanoscale dimensions with high reactivity	